

2166-BN Soldering Flux

Zero-Halogen VOC-Free Organic Water Soluble Liquid Flux

Product Description

Kester 2166-BN Soldering Flux is a zero-halogen, organic flux designed for automated soldering of circuit board assemblies. This flux provides good activity for all treated copper surfaces. The absence of chlorides, bromides, phosphates and highly corrosive materials facilitates removal after soldering. 2166-BN provides better surface insulation resistance than typical water soluble fluxes, making it particularly suitable for surface mount assemblies. 2166-BN is free of volatile organic compounds. This eliminates the use of ozone depleting chemicals and volatile organic compounds contained in the flux removal solvents. 2166-BN flux produces bright, shiny solder joints and the residue after soldering is effectively removed in standard water cleaning systems.

Performance Characteristics:

- Zero-Halogen
- Chemically compatible with most solder masks and board laminates
- High ionic cleanliness and no surface insulation resistance degradation
- Classified as ORH0 per J-STD-004

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2015/863 for the stated banned substances.

Physical Properties

Specific Gravity: 1.144 ± 0.010

Antoine Paar DMA 35 @ 25 °C

Percent Solids (typical): 31

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number: 164 ± 15 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

Flash Point: >100 °C (212 °F)

Reliability Properties

Copper Mirror Corrosion: High

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: High

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: 20 ppm max

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Surface Insulation Resistivity (SIR), IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	2166-BN
Day 1	$2.1 \times 10^{11} \Omega$	$2.2 \times 10^{10} \Omega$
Day 4	$1.9 \times 10^{11} \Omega$	$3.5 \times 10^{10} \Omega$
Day 7	$1.7 \times 10^{11} \Omega$	$6.4 \times 10^{10} \Omega$

Flux Application

2166-BN can be applied to circuit boards by a spray, dip, or wave process. An air knife after the flux tank is recommended to remove excess flux if used in a dip or wave application to remove any excess flux to prevent dripping on the preheater surface.

Process Considerations

The optimum preheat temperature for most circuit assemblies is 104 to 116 °C (220 to 240 °F) as measured on the top or component side of the printed circuit board. Dwell time in the wave is typically 2 to 4 seconds for leaded alloys and 4 to 8 seconds for lead-free alloys. The conveyor speed should be adjusted to accomplish proper board contact time with the solder. Then the preheat temperatures are adjusted to achieve the required preheat top board temperatures. In the event you need further direction on the setup of your wave soldering system, please contact Kester Technical Support.

Elimination of Splattering

Since VOC-free fluxes are water-based, splattering can be a problem. Splattering occurs when water comes in contact with molten solder, so it may be necessary to use forced air to drive off the water. Manufacturers have reported that blowing hot air at 0.28 to 0.85 m³/hr (10 to 30 ft³/hr) greatly assists in drying the water off the circuit boards.

Flux Control

Specific gravity is normally the most reliable method to control the flux concentration. To check concentration, a hydrometer should be used. DI water can be used to replace evaporative losses.

Cleaning

No neutralizer, saponifiers or detergents are necessary in the water wash system for complete removal of flux residues. It is not recommended to use high mineral content tap water. Otherwise, tap, deionized or softened water may be used for cleaning. The optimum water temperature is 49 to 60 °C (120 to 140 °F), although lower temperatures may be sufficient.

Storage, Handling and Shelf Life

Because this formulation is water based, it is subject to freezing. A minimum storage temperature of 4 °C (40 °F) is recommended. If frozen, the 2166-BN is easily reconstituted by stirring at room temperature. Shelf life is 1 year from date of manufacture when handled properly and held at 4 to 25 °C (40 to 77 °F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.

Contact Information

To confirm this document is the most recent version, please contact
Assembly@MacDermidAlpha.com

North America 800 West Thorndale Avenue Itasca, IL USA 60143 Phone: +1 800.2.KESTER	Asia Pacific 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong Phone: +852.3190.3100	Europe Ganghofer Strasse 45 82216 Gernlinden, Germany Phone: +49 (0) 8142 4785 0
---	--	--

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "®" and "™" are registered trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.